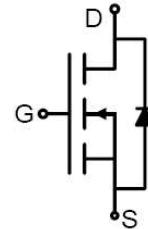
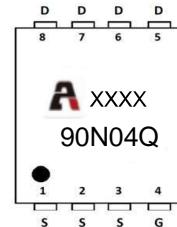


## Features

- 40V,80A
- $R_{DS(ON)} < 5.5m\Omega @ V_{GS}=10V$  TYP:4.2m $\Omega$
- $R_{DS(ON)} < 10m\Omega @ V_{GS}=4.5V$  TYP:6.5m $\Omega$
- Lead free and Green Device Available
- Excellent RDS(ON) and Low Gate Charge
- Lead free product Fast switching speed



Schematic Diagram



Marking and pin Assignment

## Applications

- Load Switch
- PWM Application
- Power management

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
90N04Q	AP90N04Q	PDFN3X3	-	-	5000

## ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_a = 25^\circ C$ )	$I_D$	80	A
Continuous Drain Current ( $T_a = 100^\circ C$ )	$I_D$	52	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	320	A
Power Dissipation ( $T_a = 25^\circ C$ )	$P_D$	77	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.5	$^\circ C/W$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	52	$^\circ C/W$
Junction Temperature	$T_J$	175	$^\circ C$
Storage Temperature	$T_{STG}$	-50~+175	$^\circ C$

**MOSFET ELECTRICAL CHARACTERISTICS( $T_a=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40	-	-	V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
Gate-body leakage current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	$\pm 100$	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.5	2.2	V
Drain-source on-resistance <sup>(2)</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	-	4.2	5.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$		6.5	10	
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	3042	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	386	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	232	-	
<b>Switching characteristics</b>						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 20\text{V}, I_D = 30\text{A}, R_L = 1\Omega, R_G = 3\Omega$ $V_{\text{GS}} = 10\text{V}$	-	8	-	$\text{ns}$
Turn-on rise time	$t_r$		-	18	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	24	-	
Turn-off fall time	$t_f$		-	14	-	
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 20\text{V}, I_D = 30\text{A},$ $V_{\text{GS}} = 10\text{V}$	-	57	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	9	-	
Gate-Drain Charge	$Q_{gd}$		-	11	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, V_{\text{GS}} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
Diode Forward current	$I_S$	$T_c = 25^\circ\text{C}$	-	-	80	A
Body Diode Reverse Recovery Time	$\text{trr}$	$T_J = 25^\circ\text{C}, IF = 5\text{A}, di/dt = 100\text{A/us}$		22		$\text{ns}$
Body Diode Reverse Recovery Charge	$Q_{rr}$	$T_J = 25^\circ\text{C}, IF = 5\text{A}, di/dt = 100\text{A/us}$		11		$\text{uc}$

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Test Circuit

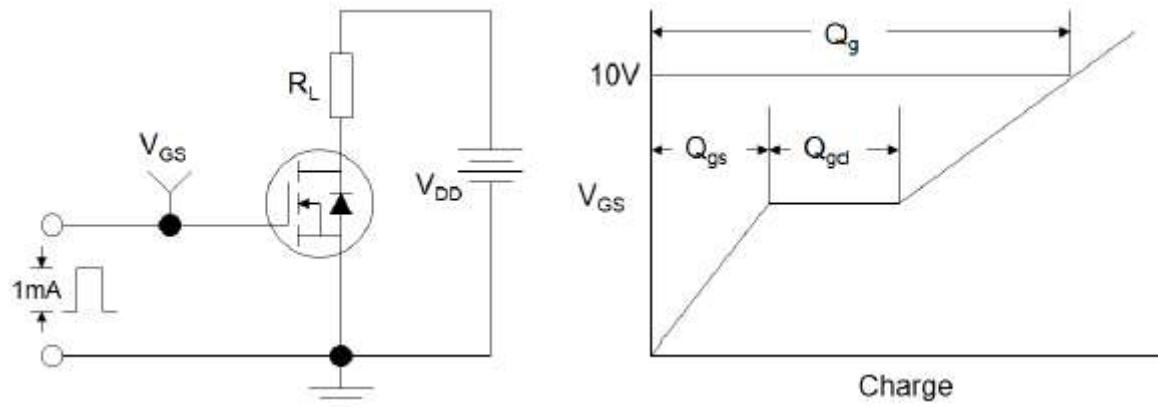


Figure1:Gate Charge Test Circuit & Waveform

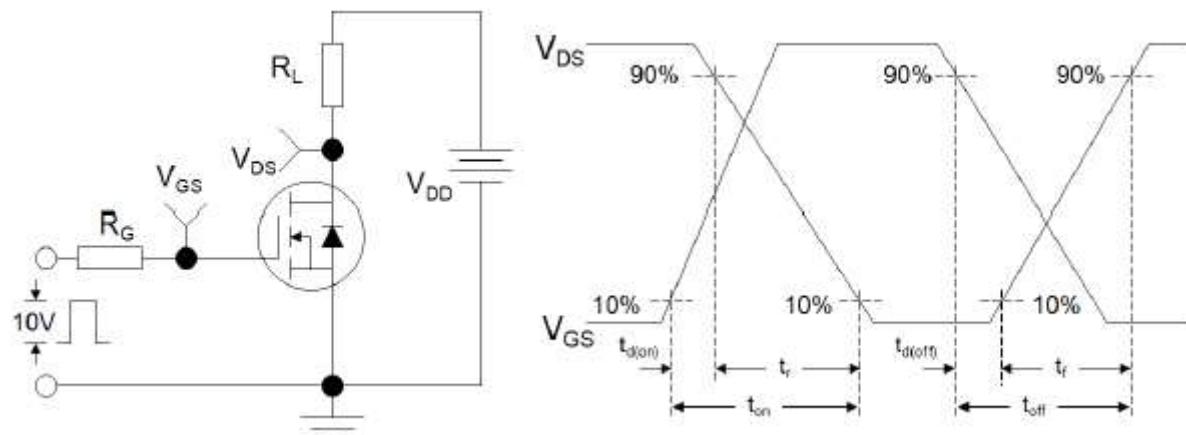


Figure 2: Resistive Switching Test Circuit & Waveforms

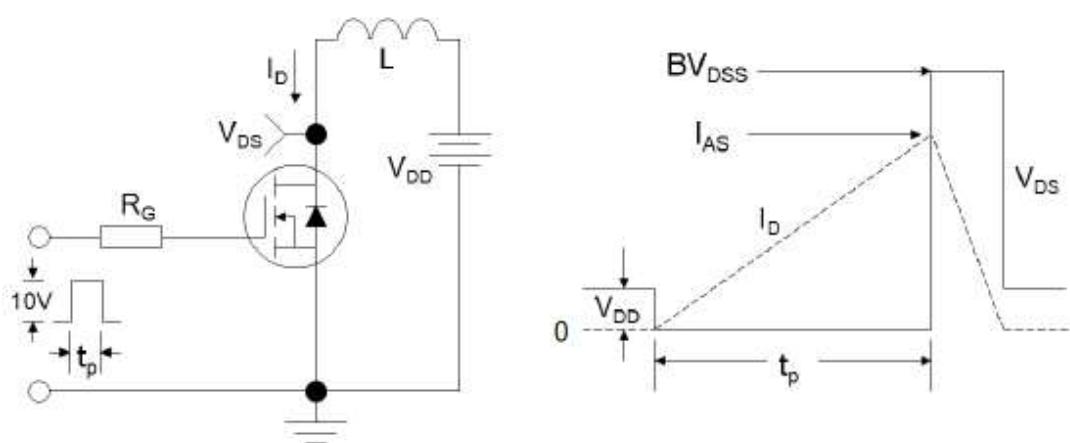
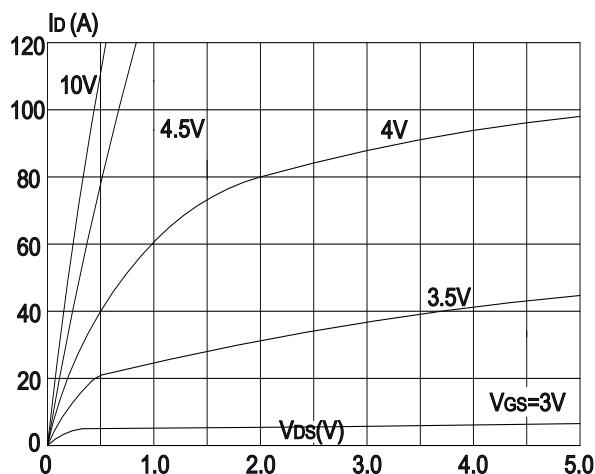


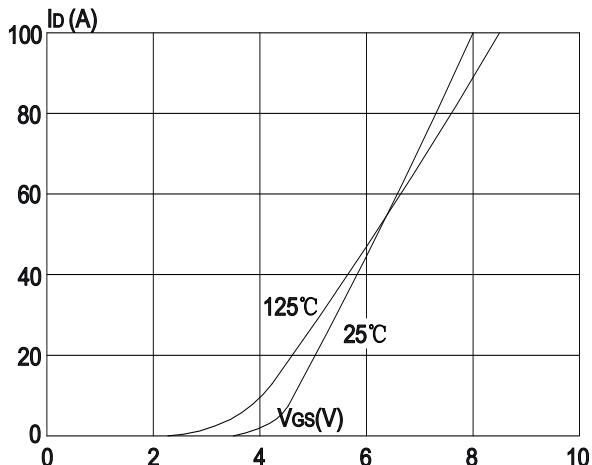
Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

## Typical Performance Characteristics

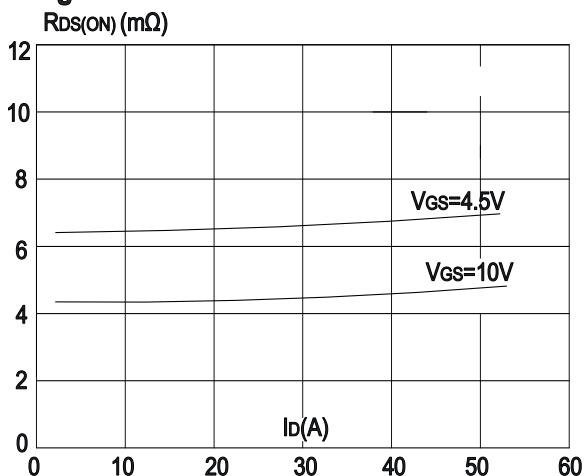
**Figure 1:** Output Characteristics



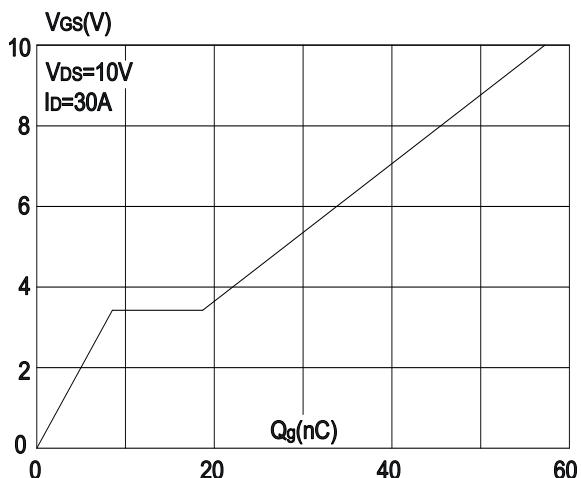
**Figure 2:** Typical Transfer Characteristics



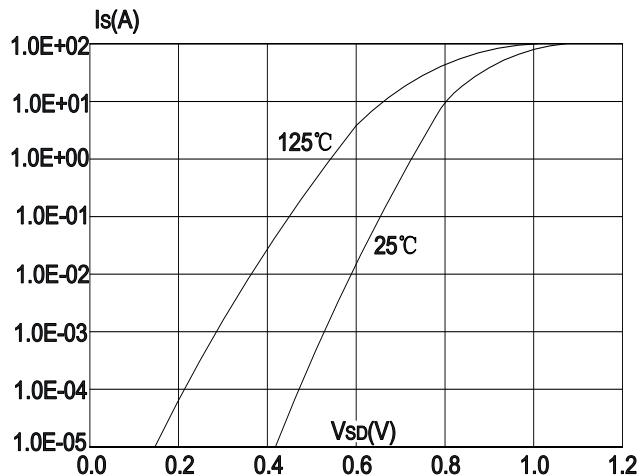
**Figure 3:** On-resistance vs. Drain Current



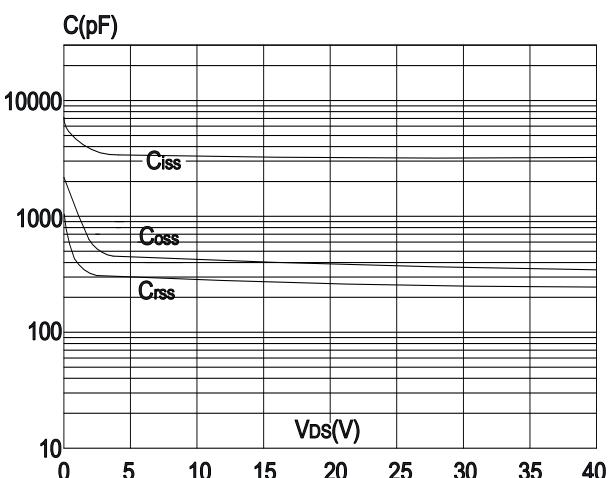
**Figure 5:** Gate Charge Characteristics



**Figure 4:** Body Diode Characteristics

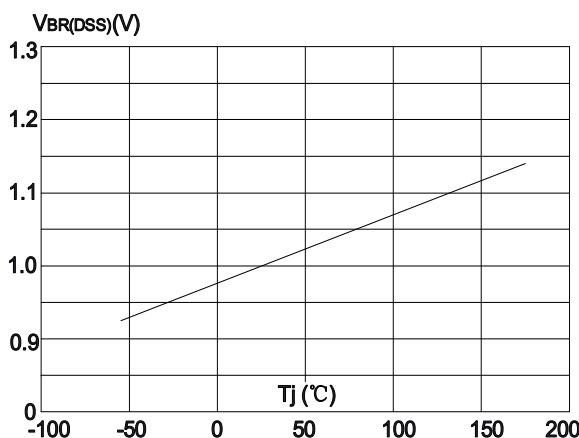


**Figure 6:** Capacitance Characteristics

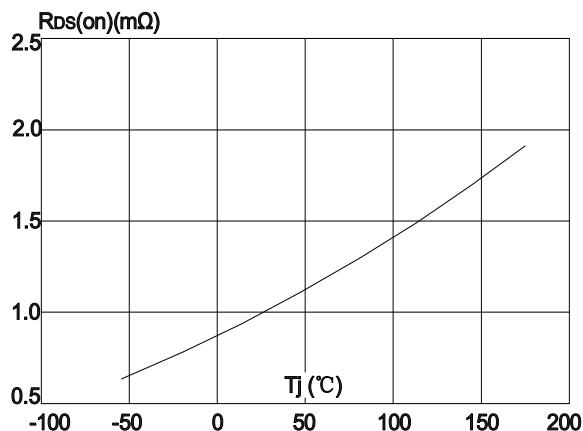


## Typical Performance Characteristics

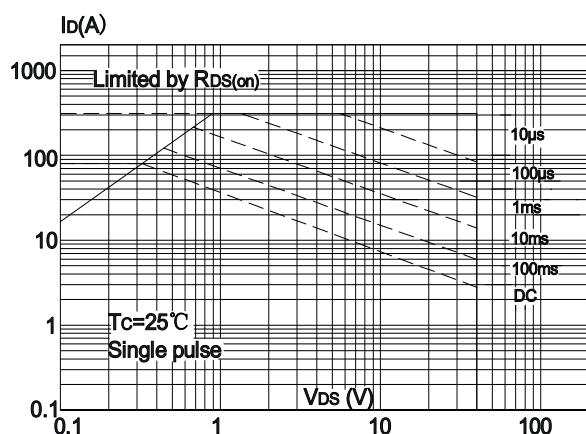
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



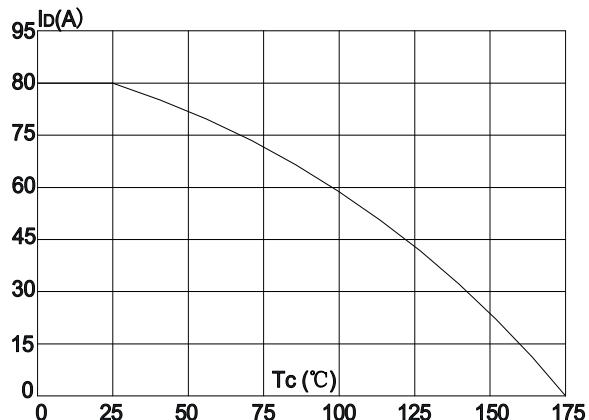
**Figure 8: Normalized on Resistance vs. Junction Temperature**



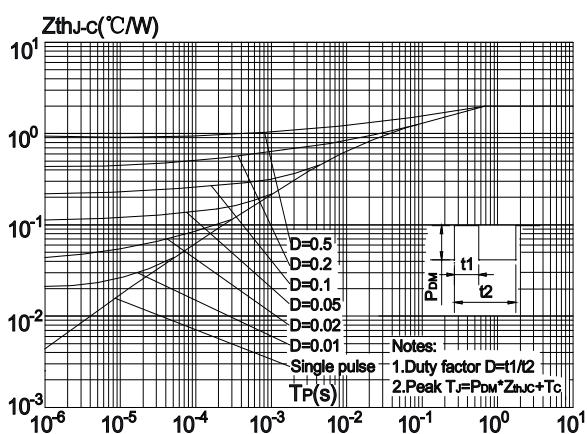
**Figure 9: Maximum Safe Operating Area**



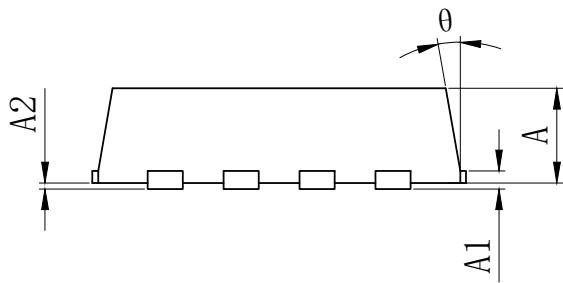
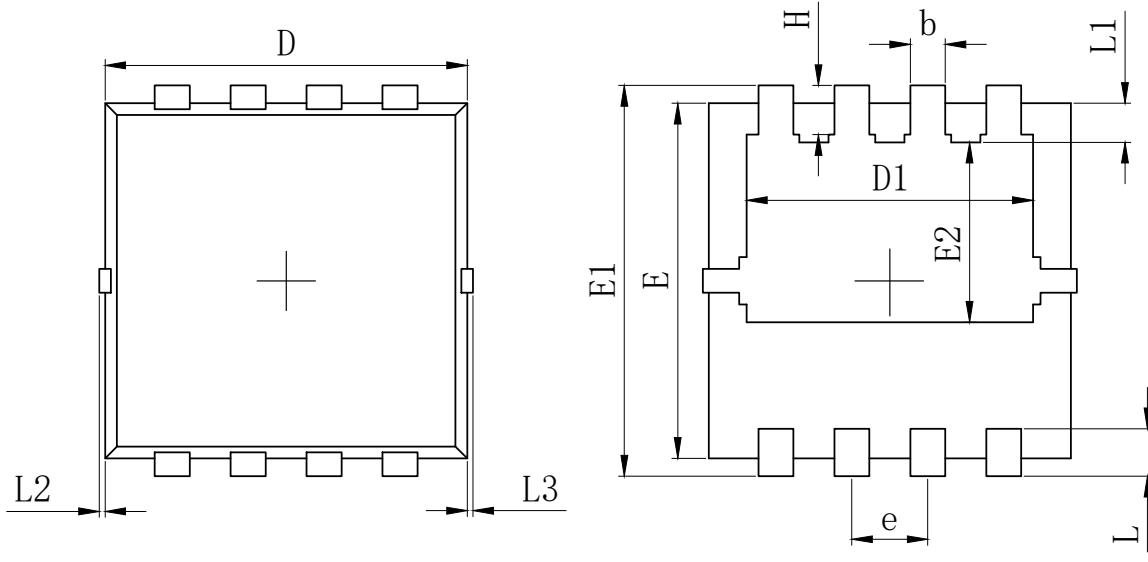
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



**Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**



### Package Mechanical Data



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.700	0.800	0.900
A1	0.152 REF.		
A2	0~0.05		
D	3.000	3.100	3.200
D1	2.300	2.450	2.600
E	2.900	3.000	3.100
E1	3.150	3.300	3.450
E2	1.320	1.520	1.720
b	0.200	0.300	0.400
e	0.550	0.650	0.750
L	0.300	0.400	0.500
L1	0.180	0.330	0.480
L2	0~0.100		
L3	0~0.100		
H	0.315	0.415	0.515
θ	8°	10°	12°